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APPLICANTS

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** CONTINUING DATA *****

This application is a DIV of 09/722,467 11/28/2000 PAT 6,657,306 *9/B*
which is a DIV of 09/321,534 05/28/1999 PAT 6,235,624

** FOREIGN APPLICATIONS *****

JAPAN 10-151800 06/01/1998

JAPAN 10-258830 09/11/1998

in 9/722,467 9/B

IF REQUIRED, FOREIGN FILING LICENSE GRANTED

** 11/14/2003

Foreign Priority claimed 35 USC 119 (a-d) conditions met Verified and Acknowledged	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance <i>William M. Brewster</i> Examiner's Signature Initials	STATE OR COUNTRY JAPAN	SHEETS DRAWING 7	TOTAL CLAIMS 16	INDEPENDENT CLAIMS 6
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ADDRESS

22852

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TITLE

Paste including a mixture of powders, connection plug, burying method, and semiconductor device manufacturing method

FILING FEE	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT	<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time)
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